T-1 3/4 (5mm) FULL COLOR LED LAMP

Part Number: WP154A4SUREQBFZGC

Hyper Red
Blue
Green

Features
- Uniform light output.
- Low power consumption.
- Long life-solid state reliability.
- RoHS compliant.

Descriptions
- The Hyper Red source color devices are made with AlGaN on GaAs substrate Light Emitting Diode.
- The Blue source color devices are made with InGaN Light Emitting Diode.
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.
- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions

Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25 (0.01") unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
Absolute Maximum Ratings at TA=25°C

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Blue</th>
<th>Green</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>Power dissipation</td>
<td>75</td>
<td>120</td>
<td>102.5 mA</td>
</tr>
<tr>
<td>DC Forward Current</td>
<td>30</td>
<td>30</td>
<td>25 mA</td>
</tr>
<tr>
<td>Peak Forward Current [1]</td>
<td>200</td>
<td>150</td>
<td>150 mA</td>
</tr>
<tr>
<td>Reverse Voltage</td>
<td>5</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>Operating/Storage Temperature</td>
<td>-40°C To +85°C</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Lead Solder Temperature [2]</td>
<td>260°C For 3 Seconds</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Lead Solder Temperature [3]</td>
<td>260°C For 5 Seconds</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.
WP154A4SUREQBFZGC
Hyper Red

- Relative Intensity vs. Wavelength

- Forward Current vs. Forward Voltage
- Relative Intensity vs. Forward Current
- Forward Current vs. Ambient Temperature
- Relative Intensity vs. Ambient Temperature

Spatial Distribution
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PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)

   ![Diagram](Fig. 1)

   "○" Correct mounting method "×" Incorrect mounting method

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)

3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

   ![Diagram](Fig. 2) ![Diagram](Fig. 3) ![Diagram](Fig. 4)

4. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)

5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
6. Do not bend the leads more than twice. (Fig. 8)

7. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.

8. The tip of the soldering iron should never touch the lens epoxy.

9. Through-hole LEDs are incompatible with reflow soldering.

10. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.

11. Recommended Wave Soldering Profiles:

![Wave Soldering Profile Diagram]

Notes:
1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C.
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.